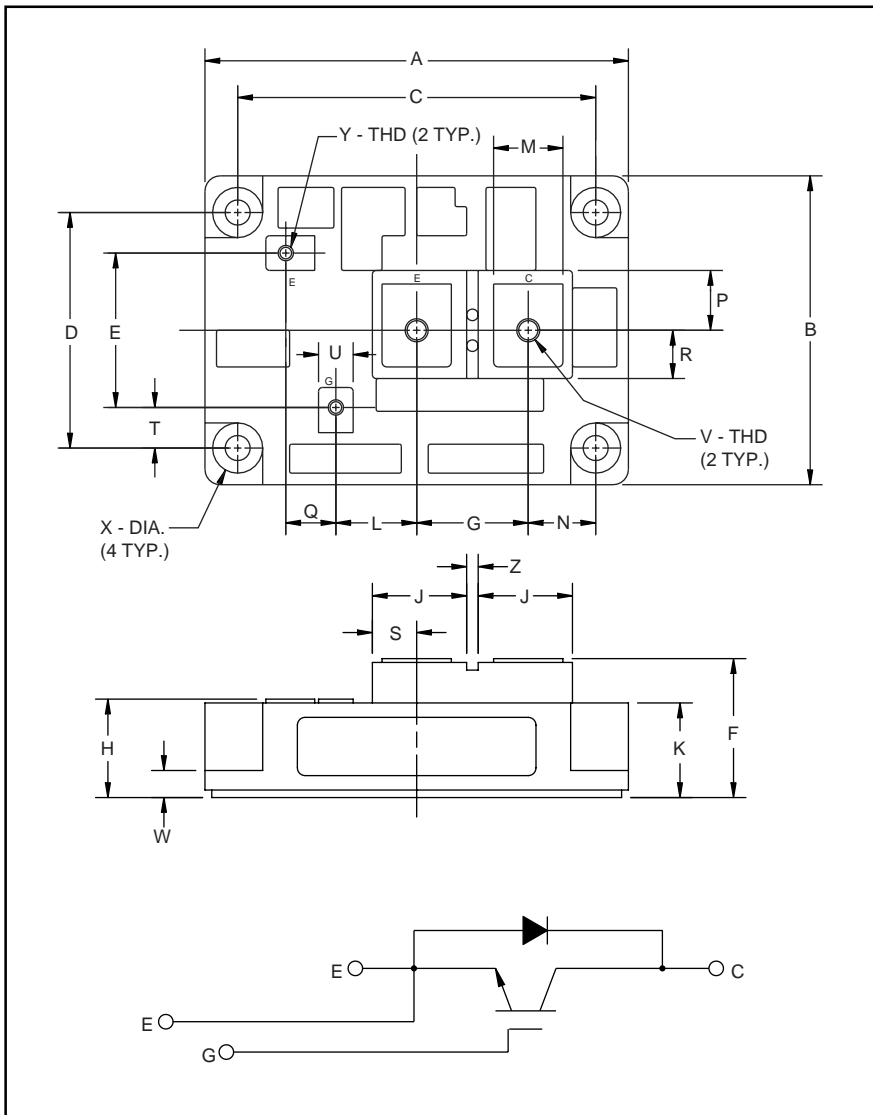


MITSUBISHI IGBT MODULES

CM600HA-28H

HIGH POWER SWITCHING USE
INSULATED TYPE



Outline Drawing and Circuit Diagram

Dimensions	Inches	Millimeters
A	4.33	110.0
B	3.15	80.0
C	3.66±0.008	93.0±0.25
D	2.44±0.008	62.0±0.25
E	1.57	40.0
F	1.42 Max.	36.0 Max.
G	1.14	29.0
H	1.00 Max.	25.5 Max.
J	0.94	24.5
K	0.93	24
L	0.83	21.0
M	0.71	18.0

Dimensions	Inches	Millimeters
N	0.69	17.5
P	0.61	15.5
Q	0.51	13.0
R	0.49	12.5
S	0.45	11.5
T	0.43	11.0
U	0.35	9.0
V	M8 Metric	M8
W	0.28	7.0
X	0.256 Dia.	Dia. 6.50
Y	M4 Metric	M4
Z	0.12	3.0



Description:

Mitsubishi IGBT Modules are designed for use in switching applications. Each module consists of one IGBT in a single configuration with a reverse-connected super-fast recovery free-wheel diode. All components and interconnects are isolated from the heat sinking baseplate, offering simplified system assembly and thermal management.

Features:

- Low Drive Power
- Low $V_{CE(sat)}$
- Discrete Super-Fast Recovery Free-Wheel Diode
- High Frequency Operation
- Isolated Baseplate for Easy Heat Sinking

Applications:

- AC Motor Control
- Motion/Servo Control
- UPS
- Welding Power Supplies

Ordering Information:

Example: Select the complete part module number you desire from the table below -i.e. CM600HA-28H is a 1400V (V_{CES}), 600 Amper Single IGBT Module.

Type	Current Rating Amperes	V_{CES} Volts (x 50)
CM	600	28

CM600HA-28H

HIGH POWER SWITCHING USE
INSULATED TYPE

Absolute Maximum Ratings, $T_j = 25\text{ }^\circ\text{C}$ unless otherwise specified

Ratings	Symbol	CM600HU-12H	Units
Junction Temperature	T_j	-40 to 150	$^\circ\text{C}$
Storage Temperature	T_{stg}	-40 to 125	$^\circ\text{C}$
Collector-Emitter Voltage (G-E SHORT)	V_{CES}	1400	Volts
Gate-Emitter Voltage (C-E SHORT)	V_{GES}	± 20	Volts
Collector Current ($T_c = 25^\circ\text{C}$)	I_C	600	Amperes
Peak Collector Current ($T_j \leq 150^\circ\text{C}$)	I_{CM}	1200*	Amperes
Emitter Current** ($T_c = 25^\circ\text{C}$)	I_E	600	Amperes
Peak Emitter Current**	I_{EM}	1200*	Amperes
Maximum Collector Dissipation ($T_c = 25^\circ\text{C}$)	P_c	4100	Watts
Mounting Torque, M8 Main Terminal	–	8.83~10.8	N · m
Mounting Torque, M6 Mounting	–	1.96~2.94	N · m
Mounting Torque, M4 Terminal	–	0.98~1.47	N · m
Weight	–	560	Grams
Isolation Voltage (Main Terminal to Baseplate, AC 1 min.)	V_{iso}	2500	Vrms

* Pulse width and repetition rate should be such that the device junction temperature (T_j) does not exceed $T_{j(max)}$ rating.

**Represents characteristics of the anti-parallel, emitter-to-collector free-wheel diode (FWDi).

Static Electrical Characteristics, $T_j = 25\text{ }^\circ\text{C}$ unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Collector-Cutoff Current	I_{CES}	$V_{CE} = V_{CES}, V_{GE} = 0V$	–	–	2.0	mA
Gate Leakage Current	I_{GES}	$V_{GE} = V_{GES}, V_{CE} = 0V$	–	–	0.5	μA
Gate-Emitter Threshold Voltage	$V_{GE(th)}$	$I_C = 60\text{mA}, V_{CE} = 10V$	5.0	6.0	8.0	Volts
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C = 600\text{A}, V_{GE} = 15V$	–	3.1	4.2**	Volts
		$I_C = 600\text{A}, V_{GE} = 15V, T_j = 150^\circ\text{C}$	–	2.95	–	Volts
Total Gate Charge	Q_G	$V_{CC} = 800V, I_C = 600\text{A}, V_{GE} = 15V$	–	3060	–	nC
Emitter-Collector Voltage	V_{EC}	$I_E = 600\text{A}, V_{GE} = 0V$	–	–	3.8	Volts

** Pulse width and repetition rate should be such that device junction temperature rise is negligible.

Dynamic Electrical Characteristics, $T_j = 25\text{ }^\circ\text{C}$ unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Input Capacitance	C_{ies}		–	–	120	nF
Output Capacitance	C_{oes}	$V_{GE} = 0V, V_{CE} = 10V$	–	–	42	nF
Reverse Transfer Capacitance	C_{res}		–	–	24	nF
Resistive	Turn-on Delay Time	$V_{CC} = 800V, I_C = 600\text{A},$	–	–	350	ns
	Rise Time					
Load	Turn-off Delay Time	$V_{GE1} = V_{GE2} = 15V, R_G = 2.1\Omega$	–	–	700	ns
	Fall Time					
Switching Times			–	–	500	ns
Diode Reverse Recovery Time	t_{rr}	$I_E = 600\text{A}, di_E/dt = -1200\text{A}/\mu\text{s}$	–	–	300	ns
Diode Reverse Recovery Charge	Q_{rr}	$I_E = 600\text{A}, di_E/dt = -1200\text{A}/\mu\text{s}$	–	6.0	–	μC

Thermal and Mechanical Characteristics, $T_j = 25\text{ }^\circ\text{C}$ unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Thermal Resistance, Junction to Case	$R_{th(j-c)}$	Per IGBT	–	–	0.03	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction to Case	$R_{th(j-c)}$	Per FWDi	–	–	0.06	$^\circ\text{C}/\text{W}$
Contact Thermal Resistance	$R_{th(c-f)}$	Per Module, Thermal Grease Applied	–	–	0.035	$^\circ\text{C}/\text{W}$